ABSTRACT

CHEMICAL MECHANICAL PLANARIZATION (CMP) MACHINE WITH IMPROVED ARCHITECTURE

Chemical mechanical planarization (CMP) machines with improved architecture are provided. In one aspect, a chemical mechanical planarization apparatus includes a column, a first substrate carrier head system, and a second substrate carrier head system. Each of the first and second carrier head systems includes a polish arm connected to the column and a wafer carrier connected to the polish arm and configured to hold a substrate. The CMP apparatus also includes a platen configured to polish at least one of a first substrate held by the first carrier head system and a second substrate held by the second carrier head system. The column overlaps at least a portion of the platen.

FIGs. 8A & 8B